

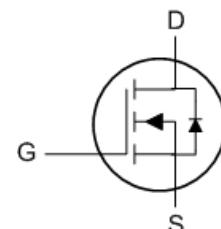
Product Summary

SOT23-3L Pin Configuration

BVDSS	RDS(on)	ID
30V	18mΩ	5.8A



- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-Source Voltage	±12	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	5.8	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	4.2	A
I _{DM}	Pulsed Drain Current ²	23.4	A
P _D @T _A =25°C	Total Power Dissipation ³	1.5	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹	---	92	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	---	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$,	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}= \pm 12\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	0.5	0.9	1.4	V
$R_{\text{DS}(\text{on})}$	Static Drain-Source on-Resistance <small>note2</small>	$V_{\text{GS}}=10\text{V}, I_D=4.2\text{A}$	-	18	25	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_D=4\text{A}$	-	26	34	
		$V_{\text{GS}}=2.5\text{V}, I_D=1\text{A}$	-	35	50	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, f=1.0\text{MHz}$	-	602	-	pF
C_{oss}	Output Capacitance		-	56	-	pF
C_{rss}	Reverse Transfer Capacitance		-	42	-	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=15\text{V}, I=4\text{A}, V_{\text{GS}}=4.5\text{V}$	-	4.8	-	nC
Q_{gs}	Gate-Source Charge		-	1.2	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	1.7	-	nC
Switching Characteristics						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=15\text{V}, I_D=4\text{A}, R_{\text{GEN}}=3\Omega, V_{\text{GS}}=4.5\text{V}$	-	12	-	ns
t_r	Turn-on Rise Time		-	52	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	17	-	ns
t_f	Turn-off Fall Time		-	10	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	6.0	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	23.2	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{\text{GS}}=0\text{V}, I_s=5.8\text{A}$	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

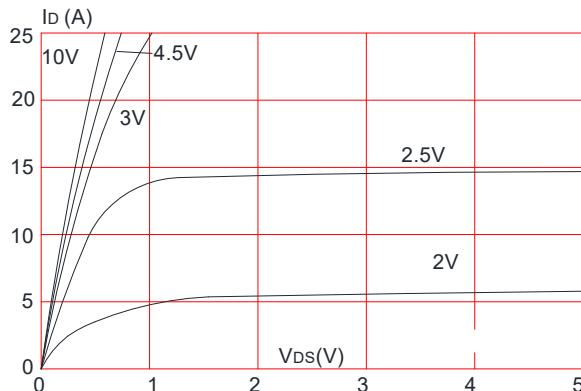


Figure 3: On-resistance vs. Drain Current

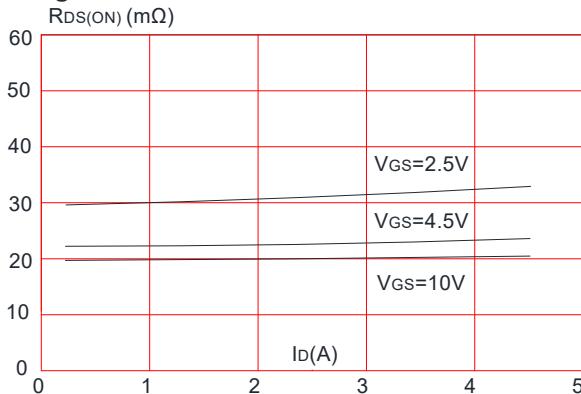


Figure 5: Gate Charge Characteristics

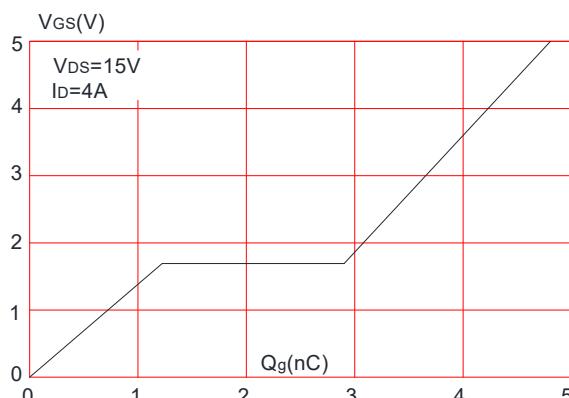


Figure 2: Typical Transfer Characteristics

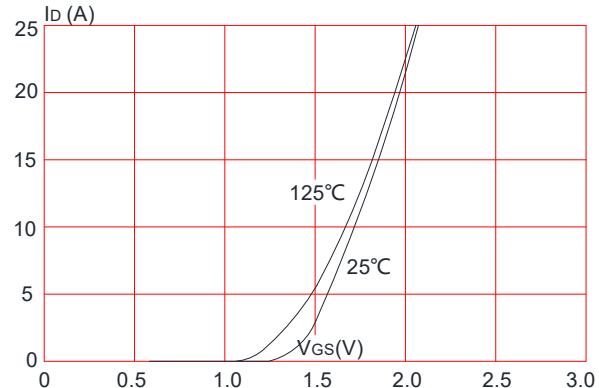


Figure 4: Body Diode Characteristics

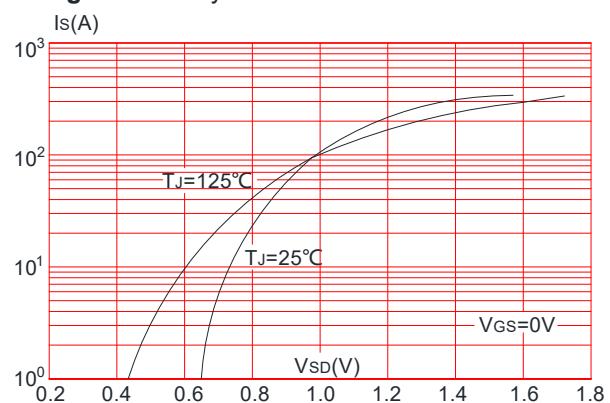


Figure 6: Capacitance Characteristics

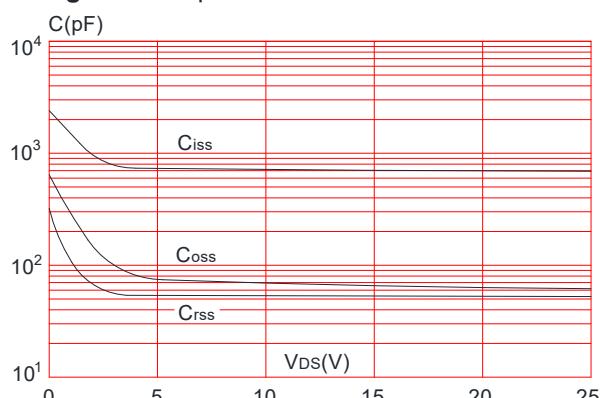


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

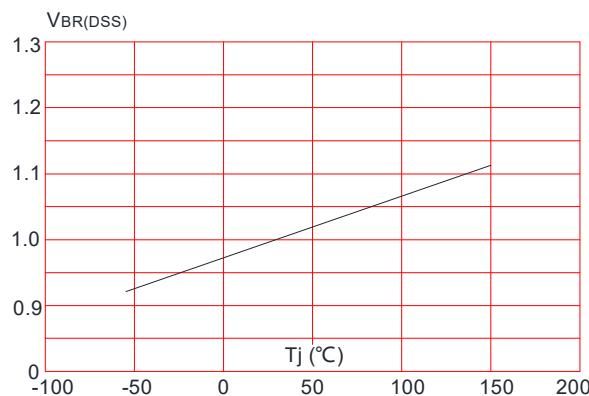


Figure 9: Maximum Safe Operating Area

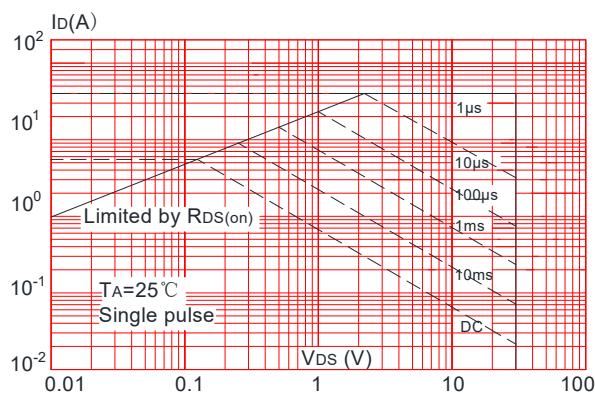


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

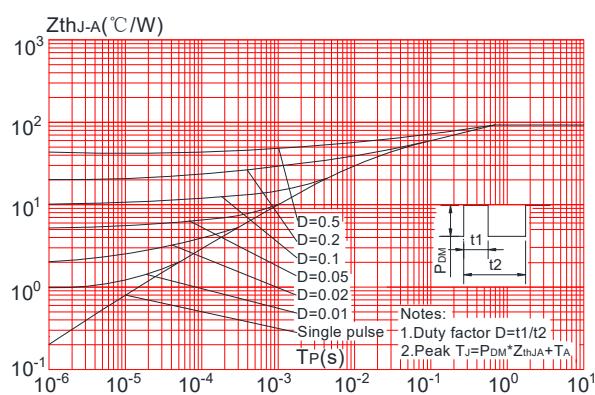


Figure 8: Normalized on Resistance vs. Junction Temperature

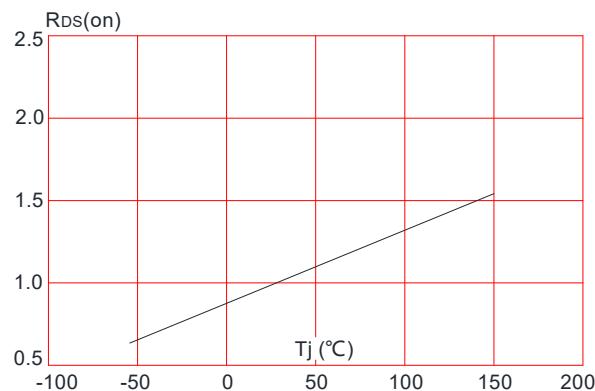
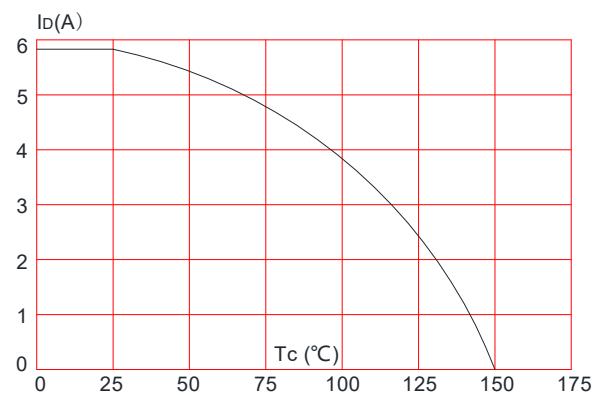
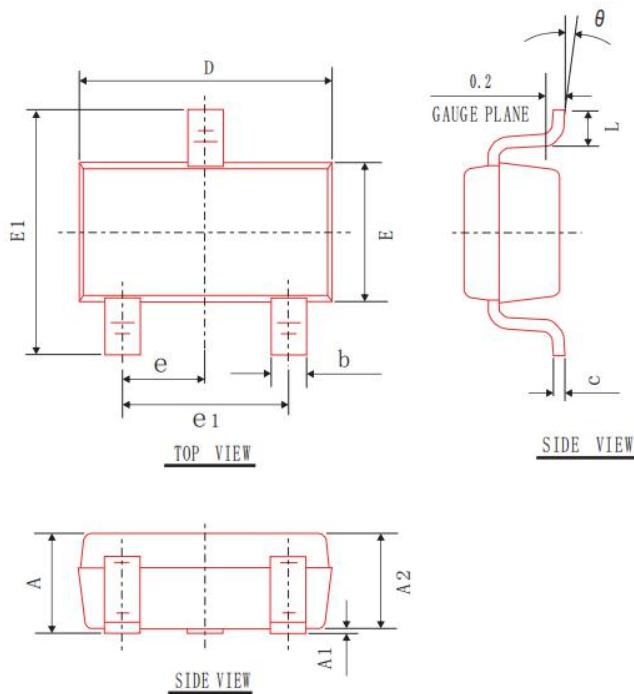


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



Package Mechanical Data-SOT-23-3L



COMMON DIMENSIONS
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	—	—	1.30
A1	0.00	0.05	0.10
A2	1.00	1.10	1.20
b	0.30	0.40	0.50
c	0.119	0.127	0.135
e1	1.80	1.90	2.00
D	2.80	2.90	3.00
E	1.50	1.60	1.70
E1	2.60	2.80	3.00
L	0.30	0.45	0.60
θ	0°	4°	8°
e	0.95BSC		